## Plastic Packages for Integrated Circuits

## Package Outline Drawing

## E18.3

18 LEAD DUAL-IN-LINE PLASTIC PACKAGE
Rev. 3, 11/11


NOTES:

1. Controlling Dimensions: INCH (Metric dimensions in parentheses).
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions are measured with the package seated in JEDEC seating plane gauge GS-3.
5. Dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch ( 0.25 mm ).
6. Dimensions are measured with the leads constrained to be perpendicular to datum $-\mathrm{C}-$.
7. Dimension measured at the lead tips with the leads unconstrained.
8. Maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch $(0.25 \mathrm{~mm})$.
9. Package outline compliant to JEDEC MS-001-AC ISSUE D.
